UNINA9910820646203321
LCP for microwave packages and modules / / [edited by] Anh-Vu H.
Pham, Morgan J. Chen, Kunia Aihara
Cambridge ; ; New York, : Cambridge University Press, 2012
1-107-22699-6
1-139-41127-6
1-280-77372-3
9786613684493
1-139-42263-4
0-511-77724-8 1-139-41961-7
1-139-41756-8
1-139-42166-2
1-139-42370-3
[1st ed.]
1 online resource (xiv, 253 pages) : digital, PDF file(s)
The Cambridge RF and microwave engineering series
TEC024000
PhamAnh-Vu H
ChenMorgan J
AiharaKunia
621.381/3
Microwave devices - Materials
Microelectronic packaging - Materials
Liquid crystal devices
Polymer liquid crystals
Inglese
Materiale a stampa
Monografia
Title from publisher's bibliographic system (viewed on 05 Oct 2015).
Includes bibliographical references and index.
Machine generated contents note: 1. Introduction; 2. Characteristics of liquid crystal polymer (LCP) Morgan J. Chen, Kunia Aihara, Cheng Chen and Anh-Vu H. Pham; 3. Fabrication techniques for processing LCP laminates; 4. LCP for wafer level chip scale MEMS; 5. LCP for surface mount interconnects, packages, and modules; 6. LCP for passive components Hai Ta, Morgan J. Chen, Kunia Aihara, Andy C. Chen, Jia-Chi Samual Chieh and Anh-Vu H. Pham; 7. LCP for system design Morgan J. Chen, Kunia Aihara, Andy C. Chen, and Chieh and

	Anh-Vu H. Pham; 8. LCP reliability.
Sommario/riassunto	A comprehensive overview of electrical design using Liquid Crystal Polymer (LCP), giving you everything you need to know to get up-to- speed on the subject. This text describes successful design and development techniques for high-performance microwave and millimeter-wave packages and modules in an organic platform. These were specifically developed to make the most of LCP's inert, hermetic, low-cost, high-frequency (DC to 110+ GHz) properties. First-hand accounts show you how to avoid various pitfalls during design and development. You'll get extensive electrical design details in areas of broadband circuit design for low-loss interconnects, couplers, splitters/combiners, baluns, phase shifters, time-delay units (TDU), power amplifier (PA) modules, receiver modules, phased-array antennas, flexible electronics, surface mounted packages, Microelectromechanical Systems (MEMS) and reliability. Ideal for engineers in the fields of RF, microwave, signal integrity, advanced packaging, material science, optical and biomedical engineering.